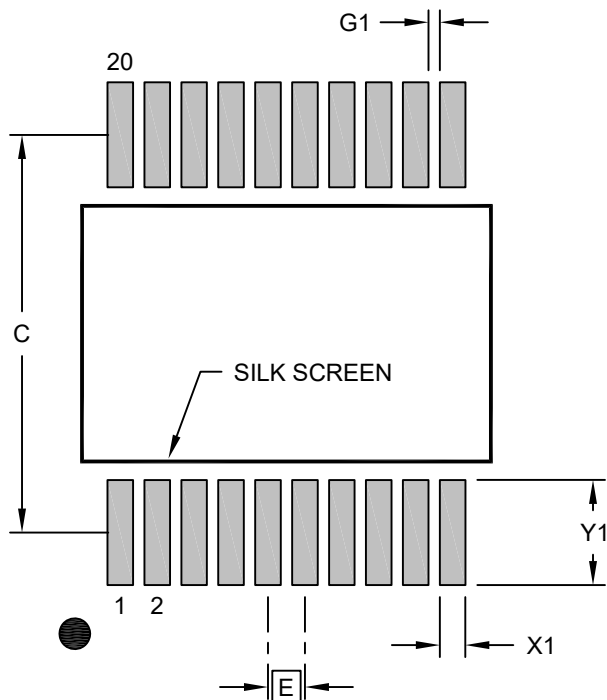


## 20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.65 BSC		
Contact Pad Spacing	C			7.00	
Contact Pad Width (X20)	X1				0.45
Contact Pad Length (X20)	Y1				1.85
Contact Pad to Center Pad (X18)	G1	0.20			

#### Notes:

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process